**IN THE CLAIMS**

*Please amend the claims as follows:*

1 – 26. (Canceled)

27. (Currently Amended) A method of manufacturing a module component comprising:

an inserting step of inserting a chip component in a first molding die;

placing a second molding die into the first molding die;

a primary molding step of filling the area between the first molding die and the second molding die with a first resin such that a first end electrode of the chip component is exposed from the first resin ~~with a first end electrode of the chip component exposed~~;

a first peeling step of peeling the first molding die from the chip component ~~at a side of inserting the chip component~~;

placing a third molding die into the second molding die;

a secondary molding step of filling the area between the [[a]] second molding die and the third molding die with a second resin such that a second end electrode of the chip component is exposed from the second resin; ~~with a second end electrode of the chip component; and~~

a second peeling step of peeling the second molding die and the third molding die from the chip component to obtain a molded element; and

a forming step of forming a circuit wiring on one side or both sides of [[a]] the molded element molded with resin, wherein the chip component is disposed according to a specified rule~~, and the chip component is molded with the resin~~.

28. (Previously Presented) A method according to claim 27, wherein the chip component is disposed in a specified position according to a matrix.

29. (Previously Presented) A method according to claim 28, wherein a dummy component having a same size as the chip component is inserted at a position where the chip component is not inserted according to the matrix.

30. (Canceled)

31. (Previously Presented) A method of claim 28, wherein the matrix has N aligned rows and M aligned columns, N being equal to or greater than 3, and M being equal to or greater than 3.